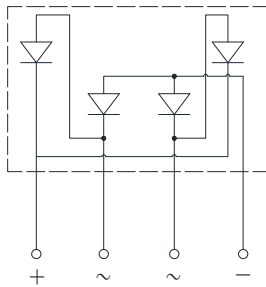
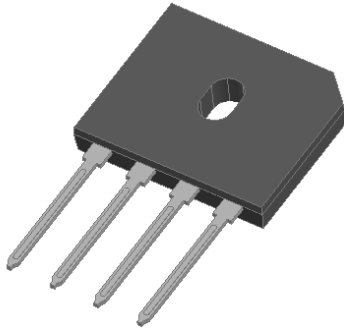


Low VF Bridge Rectifiers



Features

- UL recognition, file #E230084
- Glass passivated chip junction
- Ideal for printed circuit boards
- High surge current capability
- Low VF
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.

Mechanical Data

- **Package:** GBU
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked on body

■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GBUL2508
Device marking code			GBUL2508
Maximum Repetitive Peak Reverse Voltage	VRRM	V	800
Maximum RMS Voltage	VRMS	V	560
Maximum DC blocking Voltage	VDC	V	800
Average rectified output current @60Hz sine wave, R-load	IO	A	With heatsink Tc =125°C
			Without heatsink Ta =25°C
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, Tj=25°C	IFSM	A	450
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C			900
Current squared time @1ms≤t≤8.3ms Tj=25°C, Rating of per diode	I²t	A²S	840
Storage temperature	T _{stg}	°C	-55 ~ +150
Junction temperature	Tj	°C	-55 ~ +150
Dielectric strength @ terminals to case, AC 1 minute	V _{dis}	KV	2.5
Mounting torque @recommend torque: 5kg·cm	T _{or}	kg·cm	8.0



GBUL2508

■Electrical Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max
Instantaneous forward voltage drop per diode	V _F	V	I _{FM} =12.5A	0.80	0.90	0.92
DC reverse current at rated DC blocking voltage per diode	I _R	μA	T _j =25°C	-	0.16	5
			T _j =125°C	-	55	100
Junction capacitance	C _j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	85	170	350

■Thermal Characteristics (T_a=25°C Unless otherwise specified)

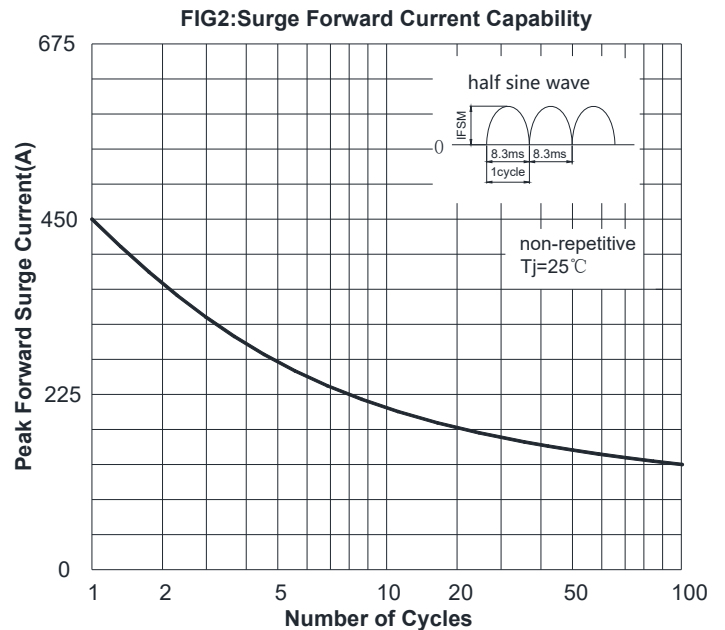
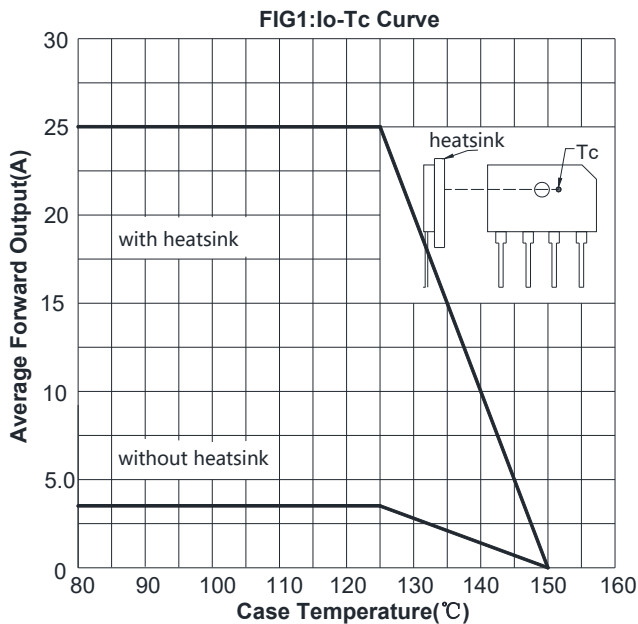
PARAMETER		SYMBOL	UNIT	GBUL2508
Thermal Resistance	Between junction and ambient, Without heatsink	R _{θJ-A}	°C/W	25.0
	Between junction and Lead, With heatsink	R _{θJ-L}		3.0
	Between junction and Case, With heatsink	R _{θJ-C}		0.5

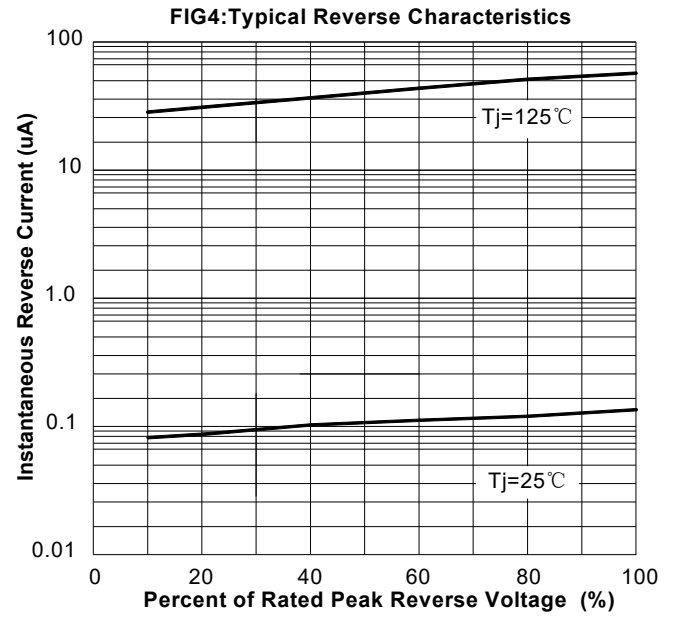
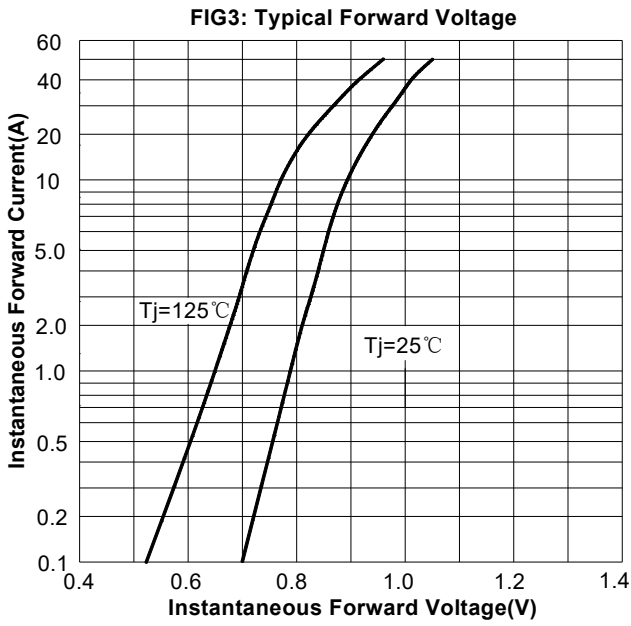
Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

■Ordering Information (Example)

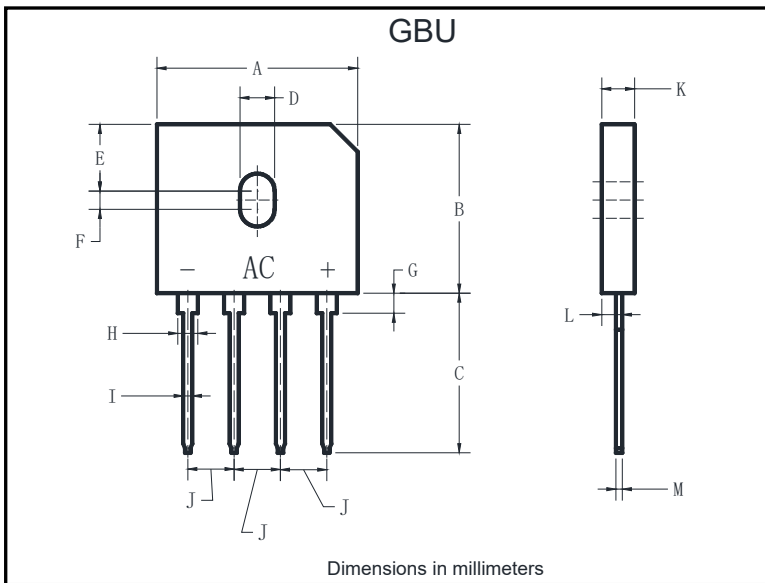
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GBUL2508	B1	Approximate 3.96	20	1000	2000	TUBE

■ Characteristics(Typical)





■ Outline Dimensions



GBU		
Dim	Min	Max
A	21.80	22.30
B	18.30	18.80
C	17.50	18.00
D	3.50	4.10
E	7.40	7.90
F	1.65	2.16
G	1.91	2.54
H	2.06	2.54
I	1.02	1.27
J	4.83	5.33
K	3.30	3.56
L	2.40	2.66
M	0.46	0.56



Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website [http:// www.21yangjie.com](http://www.21yangjie.com) , or consult your nearest Yangjie's sales office for further assistance.